

NOTES:

1. MATERIAL : HOUSING - LCP, GLASS FILLED, UL 94V-0
COLOUR : BLACK.
LATCH - NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE TABLE ON SHEET 6.
TERMINAL : COPPER ALLOY.
2. FINISHES - SEE TABLE ON SHEET 6.
3. PRODUCT SPECIFICATION : RPS-78507-001
4. PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAY,
SEE SHEET 5
5. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS
(MEASURED FROM P.C. PADS).
6. MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
7. MODULE SEATING PLANE FROM TOP OF PCB.
8. KEEP OUT ZONE RESERVED FOR LATCH.
9. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR
(INCLUDED LATCHES IN OPENING POSITION) IS MOUNTED ON THE PCB.
10. KEEP OUT ZONE AS PER JEDEC SO-014.

AMD. JEDEC STD. NO. EC NO: S2011-0743 DRWN:CCIEH 2011/02/25 CHKD:CGTAN 2011/04/19 APPR:SHLENI 2011/04/19	QUALITY SYMBOLS F=0 F=0 F=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR		
		2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	CHECKED BY CCIEH	DATE 2009/05/27	MOLEX INCORPORATED		
ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY SHLENI	DATE 2009/05/27	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78507-001	
REV		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			SHEET NO. 1 OF 6	

10 9 8 7 6 5 4 3 2 1

F

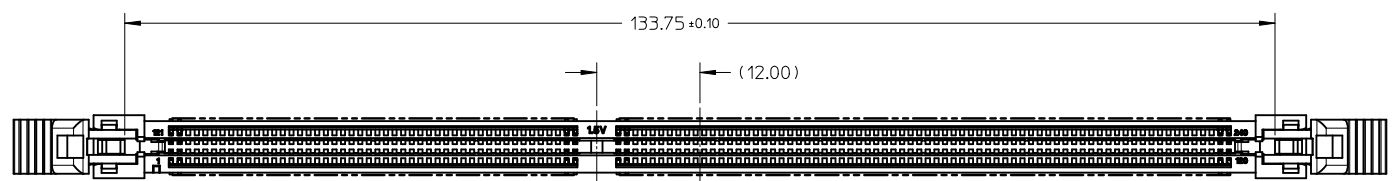
E

D

C

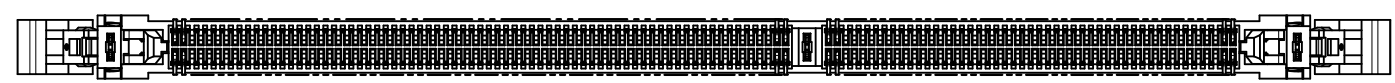
B

A

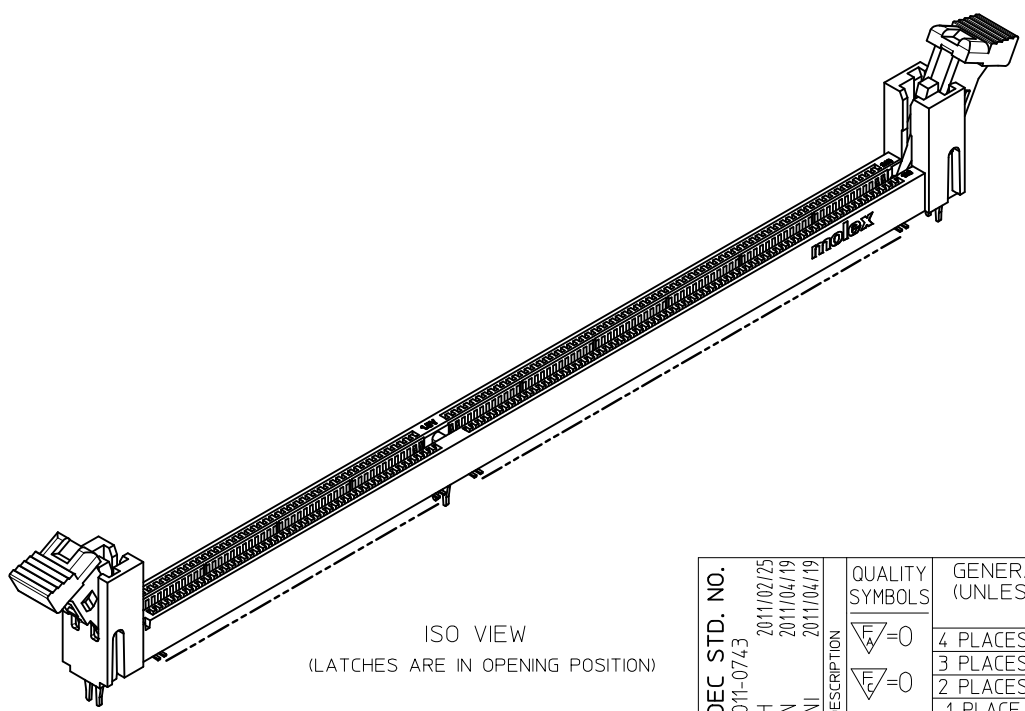


TOP VIEW
(LATCHES ARE IN OPENING POSITION)

CENTER LINE OF 128.60 MIN FEATURE



BOTTOM VIEW
(LATCHES ARE IN OPENING POSITION)



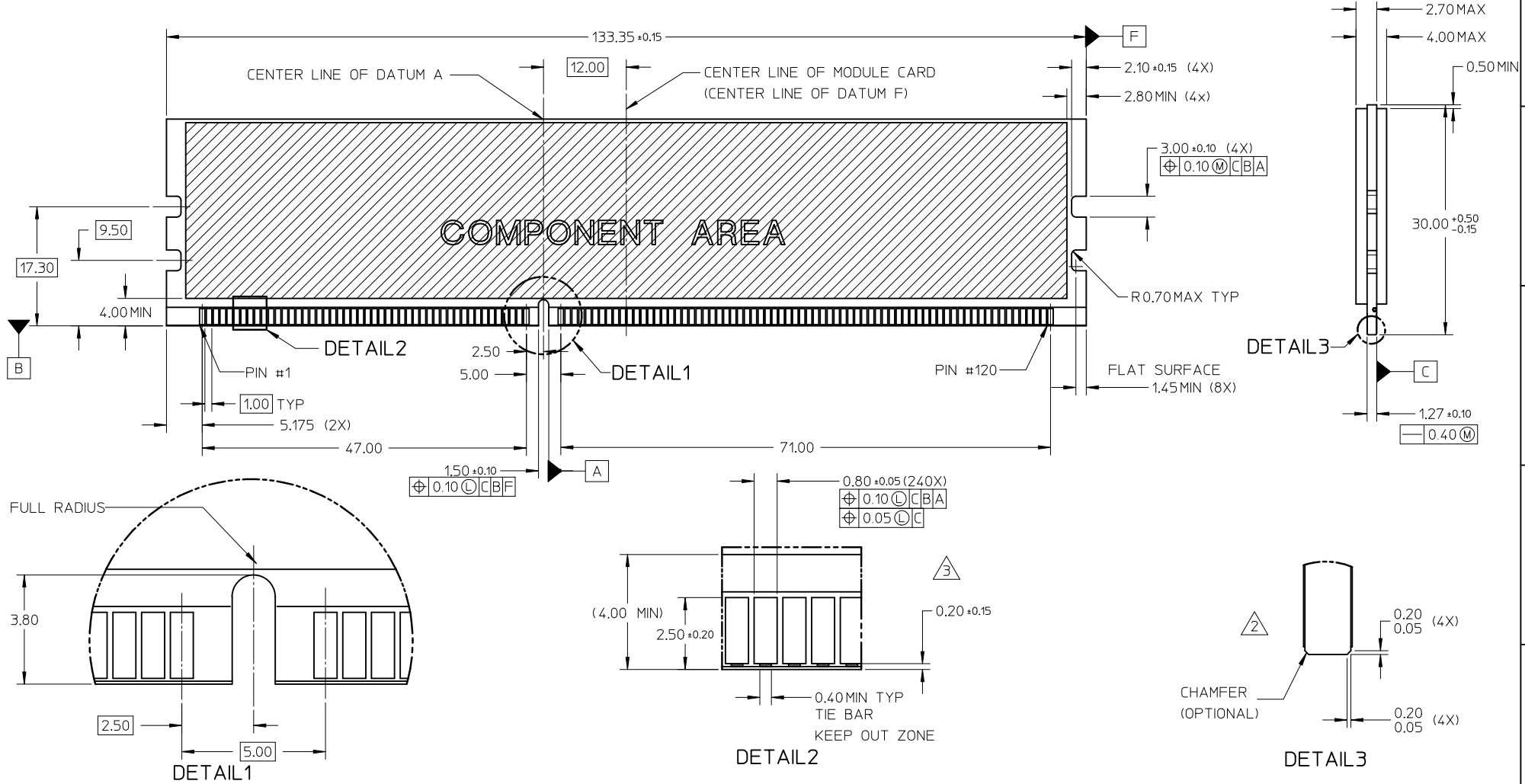
ISO VIEW
(LATCHES ARE IN OPENING POSITION)

AMD, JEDEC STD. NO. EC NO: S2011-0743 DRAWN: CCTEH 2011/02/25 CHKD: CGTAN 2011/04/19 APPR: SHLENI 2011/04/19	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm	INCH	DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR
REV 2	DESCRIPTION	4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2009/05/27	MOLEX INCORPORATED
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2009/05/27	
		2 PLACES	± 0.20	± ---	MATERIAL NO. DOCUMENT NO.		SHEET NO. 2 OF 6
		1 PLACE	± ---	± ---	SD-78507-001		
		ANGULAR ± 3 °		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

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MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE B, APRIL/06)

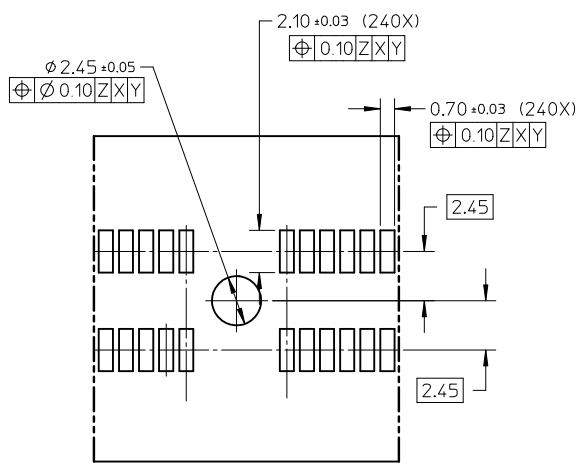
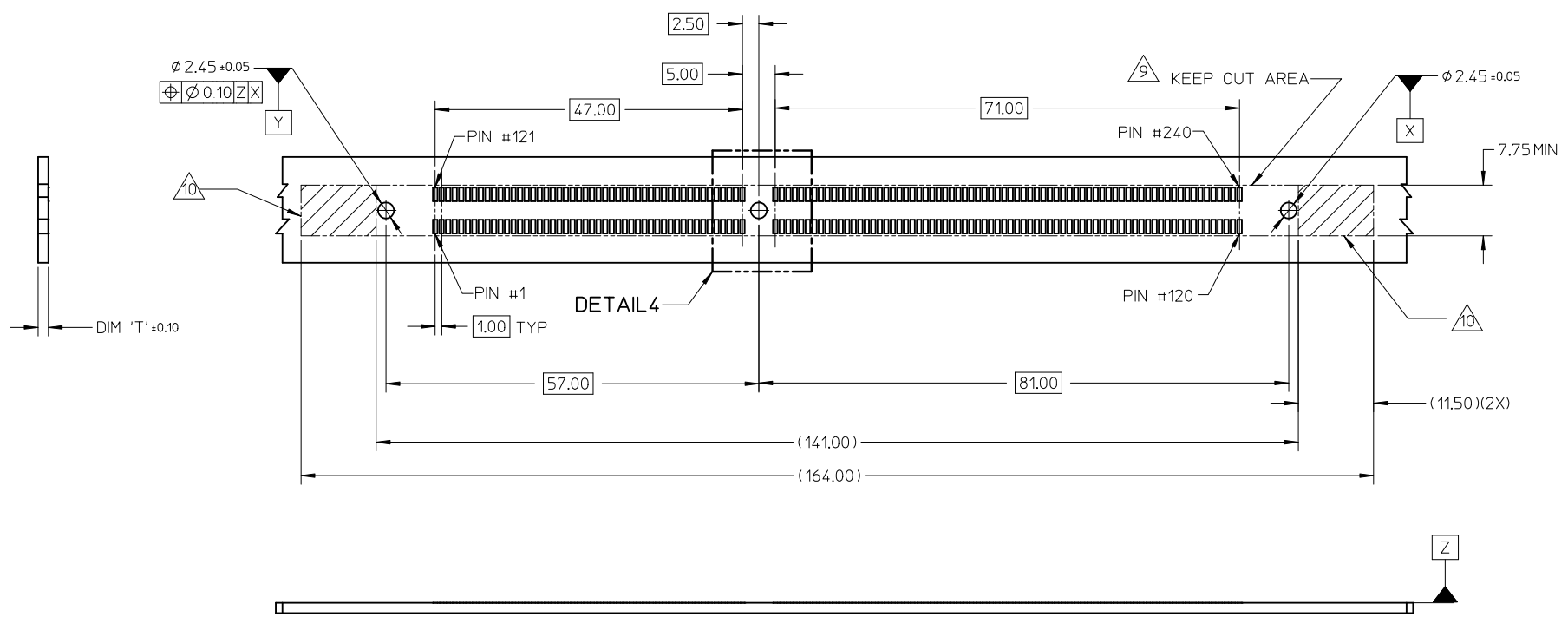


- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL.
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT.
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS.
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

AMD, JEDEC STD. NO. EC NO: S2011-0743 DRW:CCTEH 2011/02/25 CHKD:CGTAN 2011/04/19 APPR:SHLENI 2011/04/19	QUALITY SYMBOLS F _A =0 F _G =0 F _P =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm	INCH	MM ONLY	NTS	METRIC		
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
		3 PLACES	± ---	± ---	JAKEEMEW	2009/04/22	DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR	
2 PLACES	± 0.20	± ---	2 PLACES	± ---	± ---	APPROVED BY	DATE	
1 PLACE	± ---	± ---	1 PLACE	± ---	± ---	SHLENI	2009/05/27	
ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
				SEE TABLE	SD-78507-001	3 OF 6		
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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DETAIL4

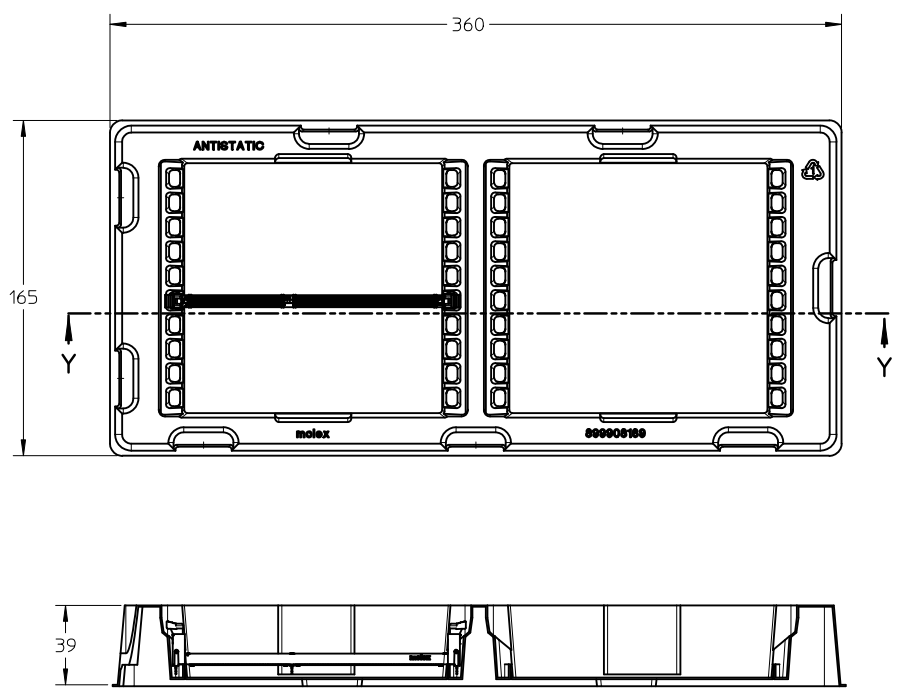
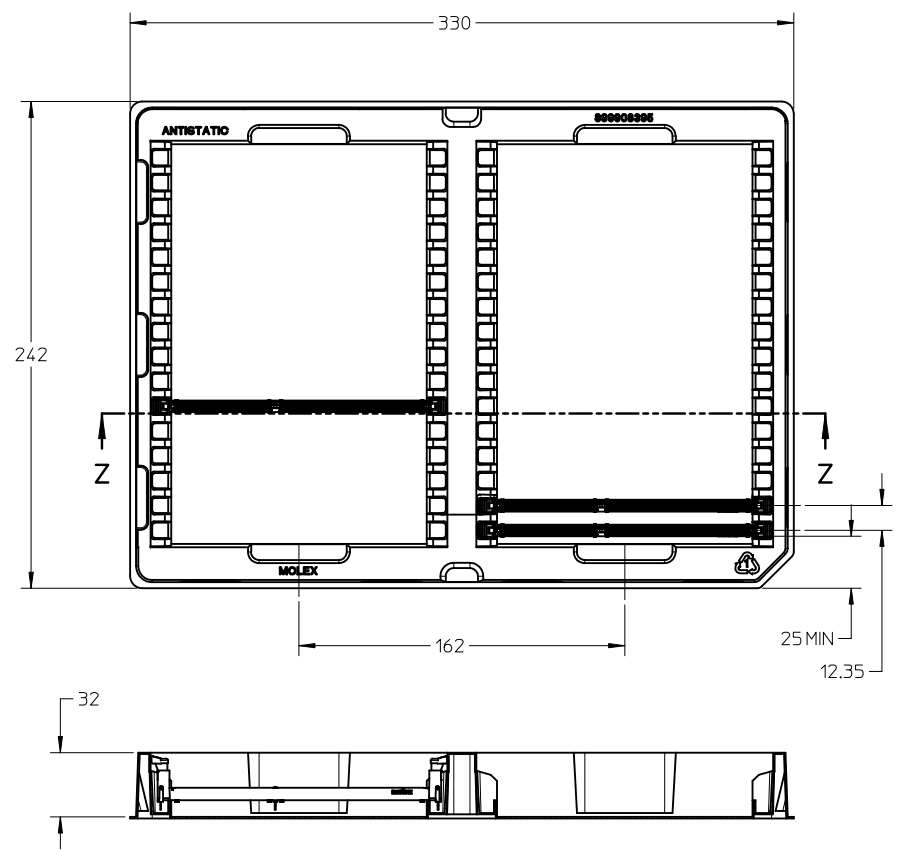
RECOMMENDED PCB THICKNESS = 1.57mm ~ 3.18mm
 RECOMMENDED STENCIL THICKNESS = 150 MICROMETERS

AMD, JEDEC STD. NO. EC NO: S2011-0743 DRWN: CCTEH 2011/02/25 CH'KD: CGTAN 2011/04/19 APPR: SHLENI 2011/04/19 REV 2	QUALITY SYMBOLS $F_{\Delta} = 0$ $F_{\Delta} = 0$ $F_{\Delta} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table> ANGULAR ± 3°		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± ---	± ---	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	± ---	± ---																		
	3 PLACES	± ---	± ---																		
2 PLACES	± 0.20	± ---																			
1 PLACE	± ---	± ---																			
DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR	CHECKED BY CCTEH	DATE 2009/05/27	MOLEX INCORPORATED	SHEET NO. 4 OF 6															
APPROVED BY SHLENI	DATE 2009/05/27	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78507-001	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS																					

9 8 7 6 5 4 3 2 1

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VIEW FOR PACKAGING TRAY



SECTION Y-Y

SECTION Z-Z

TRAY A - NO. OF CAVITY = 2 X 16 = 32PCS

AMD. JEDEC STD. NO. EC NO: S2011-0743 DRW:CCTEH CHKD:CGTAN APPR:SHLENI	REV 2	DESCRIPTION 2011/02/25 2011/04/19 2011/04/19	QUALITY SYMBOLS $F_{\Delta}=0$ $F_{\square}=0$ $F_{\nabla}=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
				mm	INCH	BROWN	TITLE X 10 = 20PCS		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				4 PLACES	\pm ---	\pm ---	JAKEEMEW	2009/04/22	DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR MOLEX INCORPORATED
				3 PLACES	\pm ---	\pm ---	CHECKED BY	DATE	
				2 PLACES	\pm 0.20	\pm ---	CCTEH	2009/05/27	
				1 PLACE	\pm ---	\pm ---	APPROVED BY	DATE	
				ANGULAR \pm 3 °		SHLENI	2009/05/27	DOCUMENT NO. SD-78507-001	SHEET NO. 5 OF 6
				SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

PART NO.	VOLTAGE KEY POS.	DIM 'X'	PLATING OPTION	LATCH COLOR	TRAY TYPE	LUBRICATION
78507-0001	CENTER (1.5V)	3.94	0.76µM (30µNCH) MIN. GOLD ON CONTACT. 2.54µM (100µNCH) MIN. PURE TIN ON SOLDER TAIL. 1.27µM (50µNCH) MIN. NICKEL UNDERPLATE.	BLACK	B	YES
78507-0002					A	
78507-0003				B		
78507-0004				A		

AMD, JEDEC STD. NO. EC NO: S2011-0743 DRWN: CCTEH 2011/02/25 CHKD: GTAN 2011/04/19 APPR: SHLENI 2011/04/19 2	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR			
		ANGULAR ± 3 °		CHECKED BY CCTEH	DATE 2009/05/27	APPROVED BY SHLENI			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	DATE 2009/05/27	MOLEX INCORPORATED		DOCUMENT NO. SD-78507-001	SHEET NO. 6 OF 6